

## Features

- Advanced Trench MOS Technology
- Super Low Gate Charge
- Green Device Available

## Product Summary

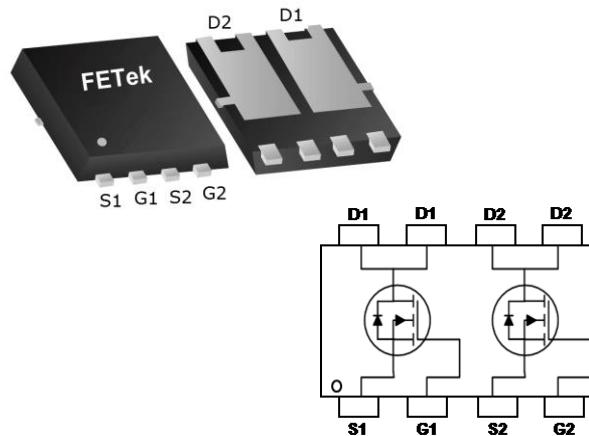


BVDSS	RDS(ON)	ID
30V	14mΩ	30A

## Applications

- Power Management in Desktop Computer
- DC/DC Converters
- Motor Control

## PRPAK3X3 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	8.8	A
I <sub>D</sub> @T <sub>A</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.5	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	65	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	24.2	mJ
I <sub>AS</sub>	Avalanche Current	22	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	20.8	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.67	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	75	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	6	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

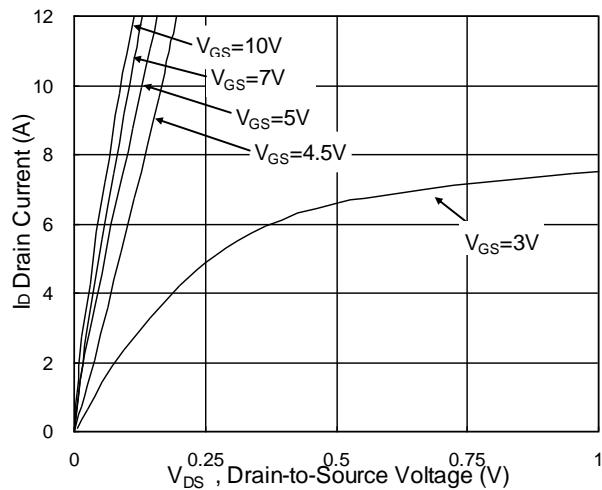
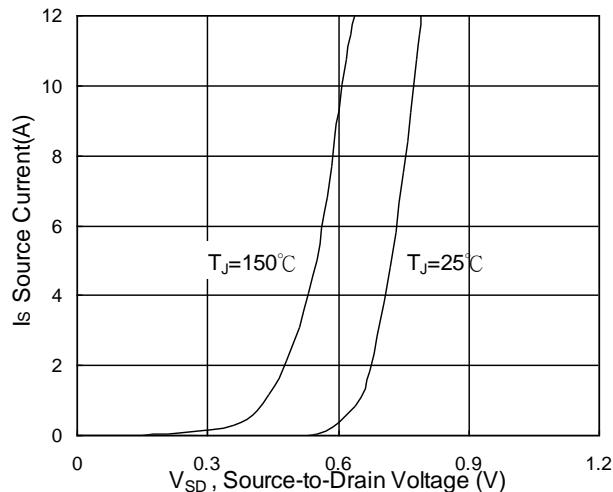
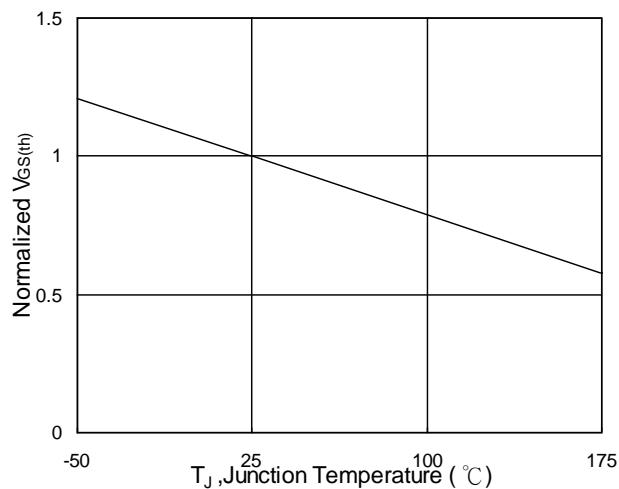
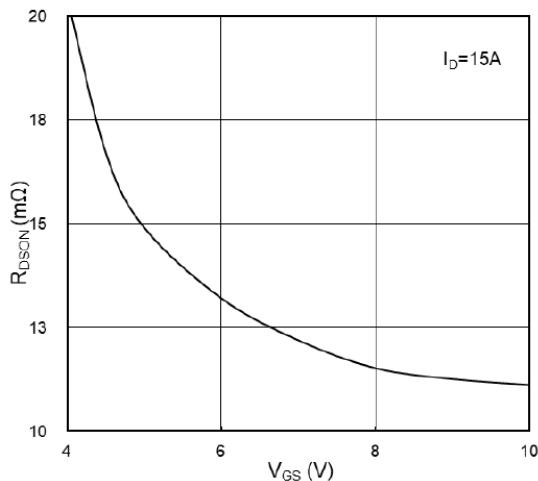
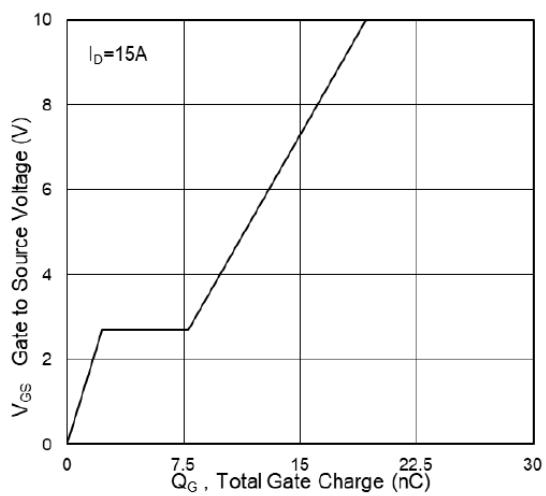
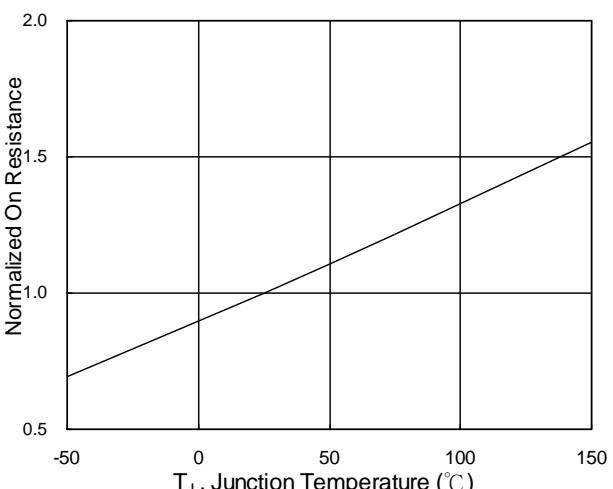
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_D=250\mu\text{A}$	30	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$\text{V}_{\text{GS}}=10\text{V}$ , $\text{I}_D=15\text{A}$	---	11	14	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=10\text{A}$	---	13.5	19.5	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$ , $\text{I}_D=250\mu\text{A}$	1.4	---	2.5	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $\text{T}_J=55^\circ\text{C}$	---	---	5	
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$ , $\text{V}_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$\text{g}_{\text{fs}}$	Forward Transconductance	$\text{V}_{\text{DS}}=5\text{V}$ , $\text{I}_D=15\text{A}$	---	24.4	---	S
$\text{R}_{\text{g}}$	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.8	---	$\Omega$
$\text{Q}_{\text{g}}$	Total Gate Charge (4.5V)	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=4.5\text{V}$ , $\text{I}_D=12\text{A}$	5.9	9.82	13.7	$\text{nC}$
$\text{Q}_{\text{gs}}$	Gate-Source Charge		1.1	2.24	3.4	
$\text{Q}_{\text{gd}}$	Gate-Drain Charge		2.8	5.54	8.3	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=15\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{R}_{\text{G}}=1.5\Omega$ $\text{I}_D=20\text{A}$	---	6.4	10	$\text{ns}$
$\text{T}_{\text{r}}$	Rise Time		---	39	59	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	21	32	
$\text{T}_{\text{f}}$	Fall Time		---	4.7	7	
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{DS}}=15\text{V}$ , $\text{V}_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	538	896	1254	$\text{pF}$
$\text{C}_{\text{oss}}$	Output Capacitance		76	126	176	
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance		65	108	151	

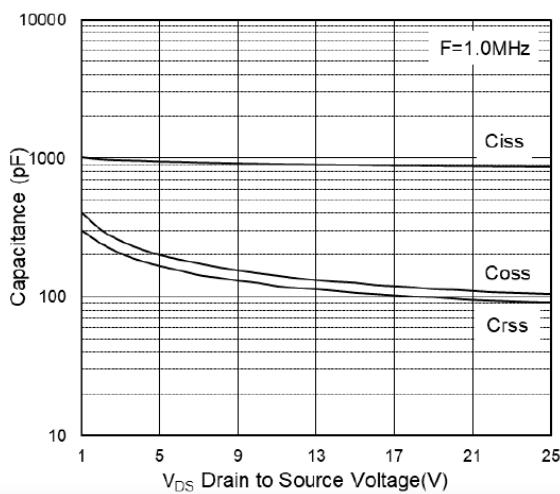
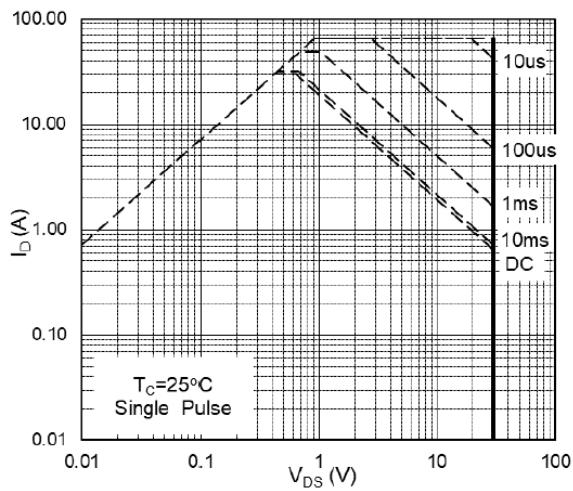
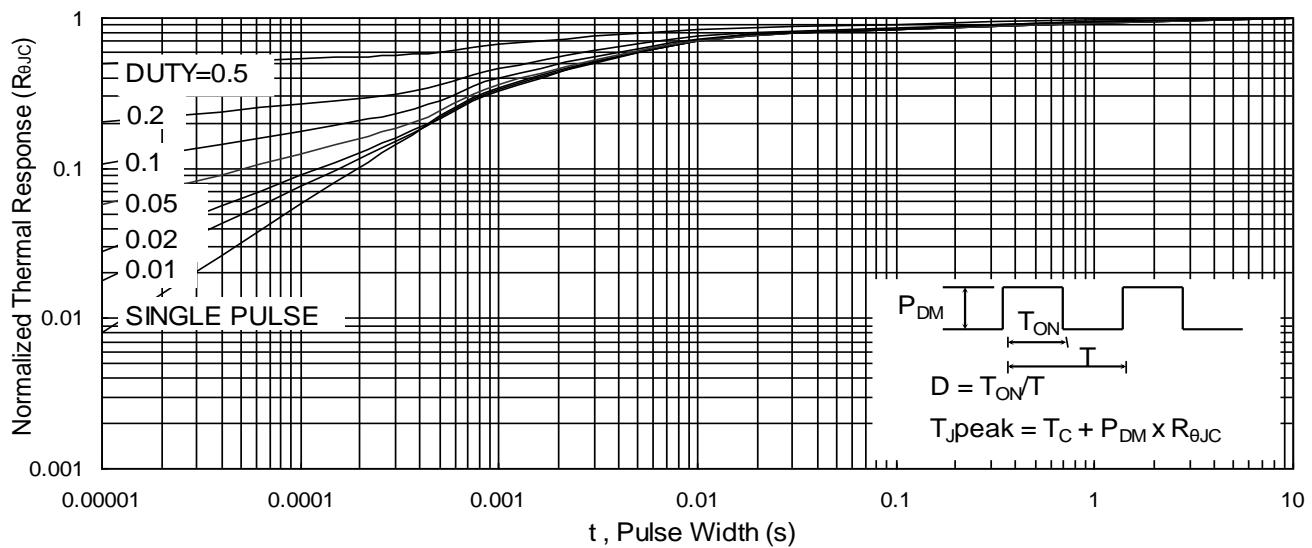
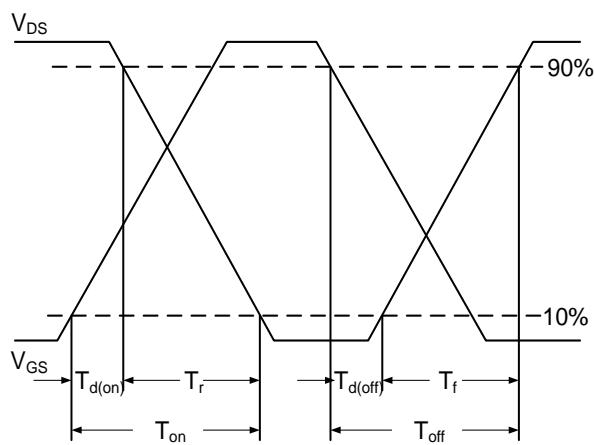
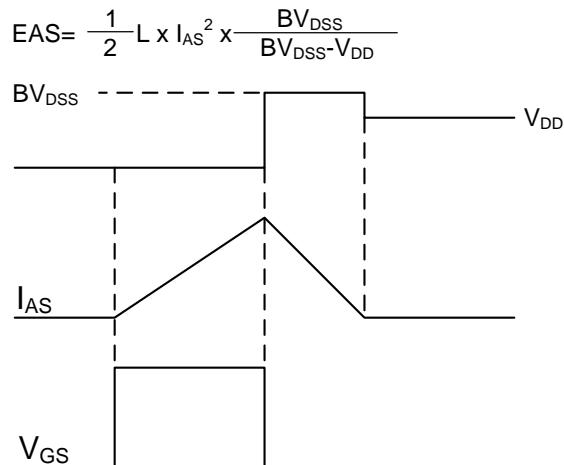
## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{I}_{\text{s}}$	Continuous Source Current <sup>1,5</sup>	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$ , Force Current	---	---	30	A
$\text{V}_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$\text{V}_{\text{GS}}=0\text{V}$ , $\text{I}_{\text{s}}=1\text{A}$ , $\text{T}_J=25^\circ\text{C}$	---	---	1	V

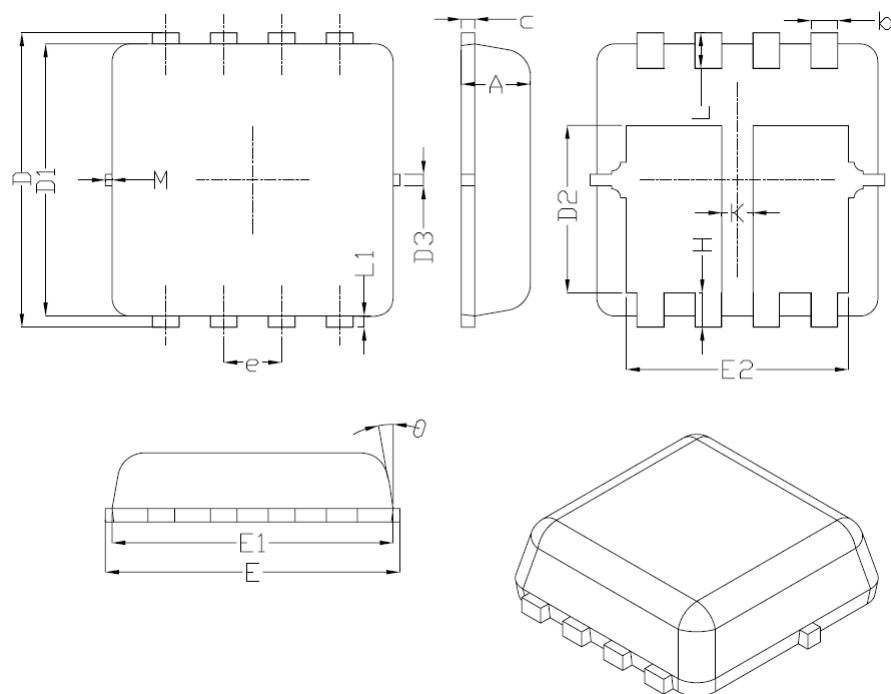
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}$ , $\text{V}_{\text{GS}}=10\text{V}$ , $\text{L}=0.1\text{mH}$ , $\text{I}_{\text{AS}}=22\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $\text{I}_{\text{D}}$  and  $\text{I}_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.3 Source Drain Forward Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.4 Gate-charge Characteristics**

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**

## PRPAK3x3-8L\_EP2 Package Outline



Symbols	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.70	0.85	0.027	0.031
b	0.25	0.39	0.010	0.015
c	0.10	0.25	0.004	0.010
D	3.20	3.45	0.126	0.136
D1	2.95	3.20	0.116	0.126
D2	1.60	1.98	0.063	0.080
D3	0.10	0.30	0.004	0.012
E	3.20	3.45	0.126	0.136
E1	3.00	3.25	0.118	0.128
E2	2.30	2.60	0.091	0.102
e	0.65 BSC		0.025 BSC	
H	0.30	0.50	0.011	0.026
θ	---	14°	---	14°
L	0.30	0.50	0.012	0.020
L1	0.13		0.005	
M	---	0.15	---	0.006
K	0.30	---	0.012	---

